SCIENTECH

(3583)

2020/6/24

Safe Harbor Statement

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- This Presentation contains certain forward-looking statements that are based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.

- Except as required by law, we undertake no obligation to update any forward –looking statements, whether as a result of new information, future events or otherwise.

Scientech Corp (3583: TT)

Company Establishment	1979/10/17
IPO	2013/3/12
Capital	NT$ 811 Million
Chairman	H.L. Hsieh
President	M.T. Hus
Products	Equipment Manufacturing、Wafer Reclaim、Trading(Agent/Distributor)

Business Overviews

Products

Future Prospect

Business Overview

Income Statement

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Units：NT $ M	2015	2016	2017	2018	2019	1Q20
Revenues	2,942	3,495	3,539	3,988	3,949	630
Gross Profit	903	1,178	1,251	1,448	1,384	242
Operating Expenses	779	835	829	935	997	221
Operating Income	124	343	423	514	387	21
Other Income and Expenses	(6)	21	(8)	26	16	(16)
Income Before Tax	119	363	415	540	403	5
Net Income	86	292	328	418	323	3
EPS	1.06	3.60	4.05	5.16	4.02	0.03
Gross Margin	30.69%	33.71%	35.36%	36.32%	35.05%	38.47%
Operating Margin	4.23%	9.80%	11.95%	12.88%	9.81%	3.35%
Income Before Tax margin	4.03%	10.40%	11.72%	13.54%	10.22%	0.77%

Business Overview

Products Mix

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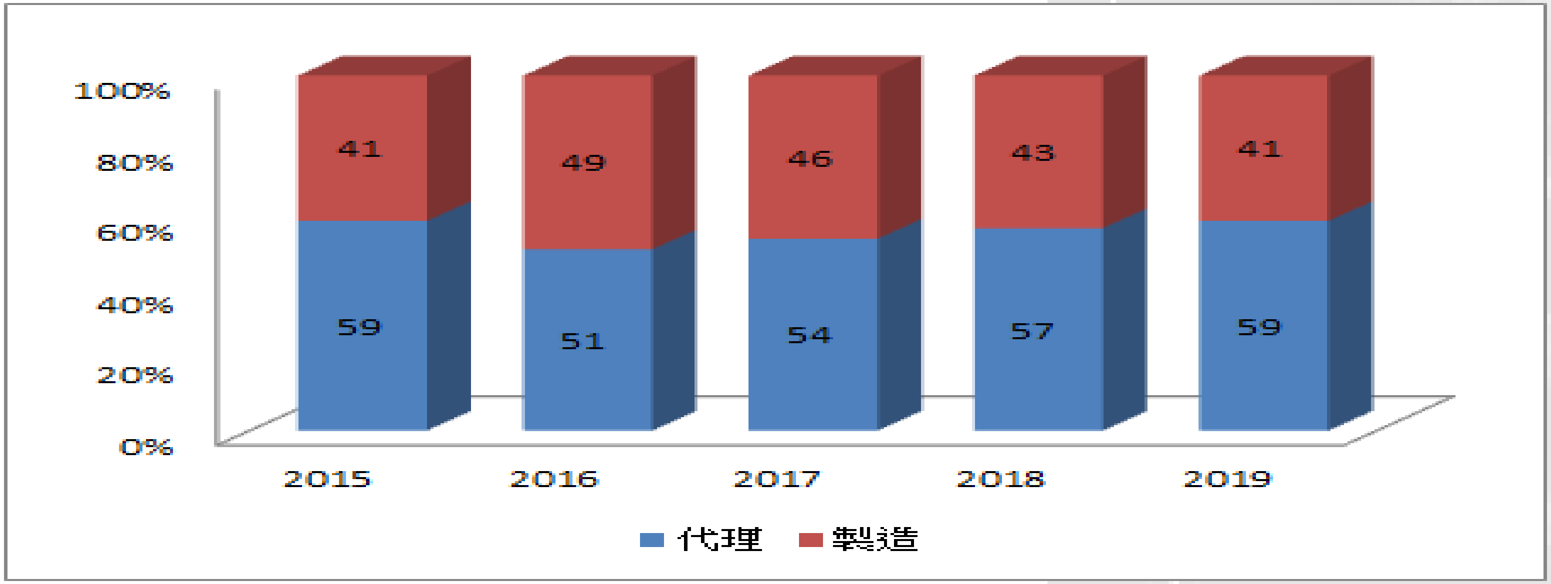
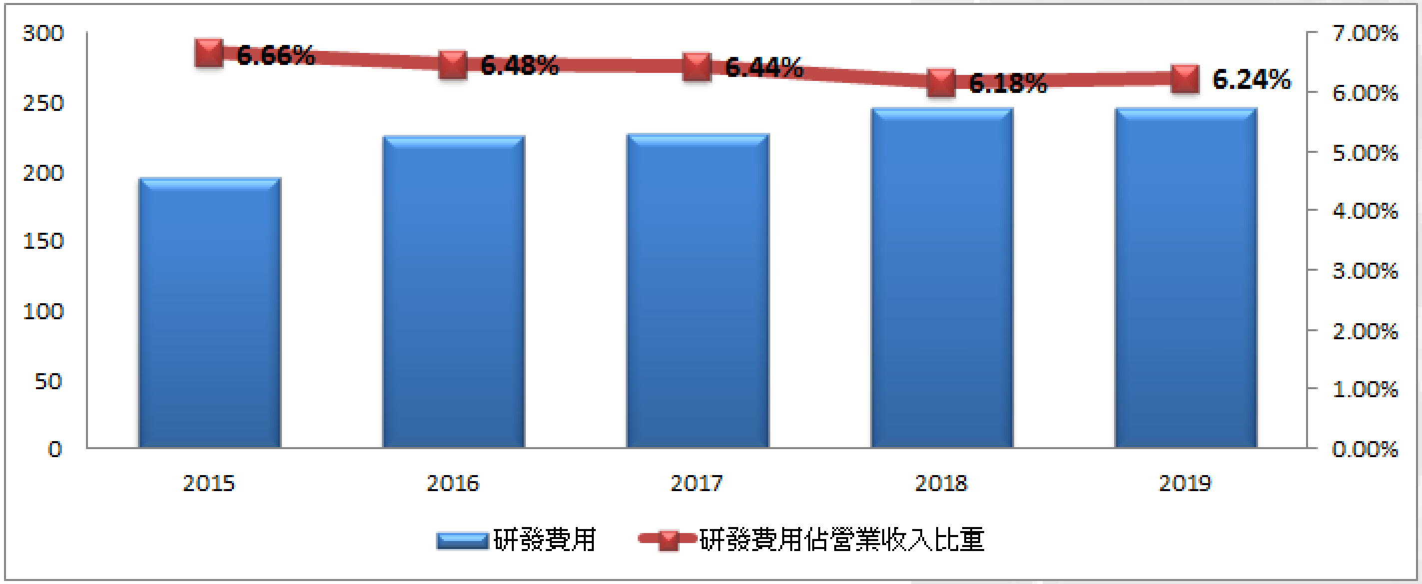
Units：%	2015	2016	2017	2018	2019	Gross Margin
Trading	59	51	54	57	59	Below Average
Manufacturing	41	49	46	43	41	Above Average

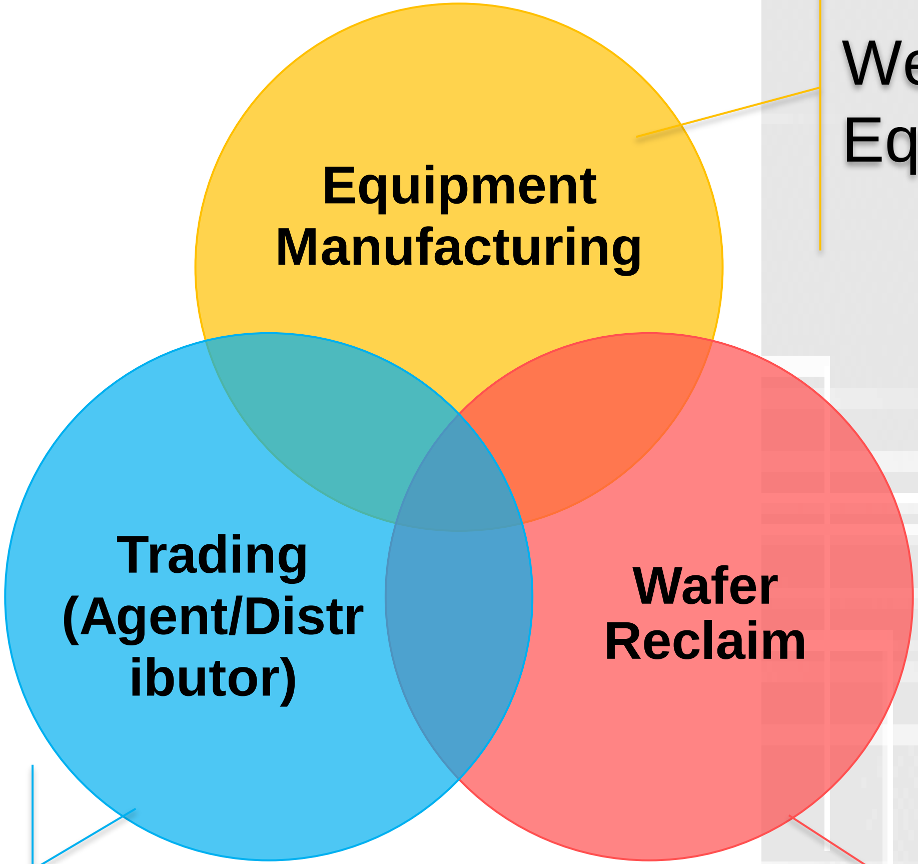


R&D Expenses

Units：NT $ M	2015	2016	2017	2018	2019
R&D Expenses	196	226	228	246	246
Expenses as % of Revenue	6.66%	6.48%	6.44%	6.18%	6.24%



Products



Equipment Manufacturing

Trading (Agent/Distributor)

Wafer Reclaim

Wet Process Equipment

Semiconductor and Optoelectronics Process Equipment

12” Wafer Reclaim

Products

Equipment Manufacturing

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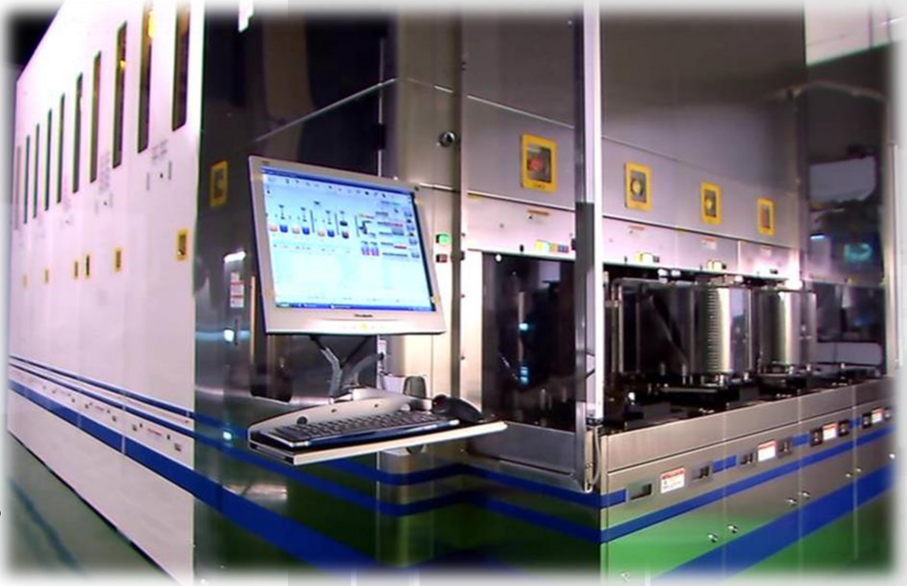
Wet process equipment

- **Single wafer/ Batch type**
  - **8”/12’ Advanced packaging** (Fan-out、 Solder Bump、Copper Pillow 、Bumping 、Gold Bump 、 RDL 、 TSV …ect)
  - **6”/ 8”/12” Front-end special process** (IoT Sensor 、 Power IC FP sensor、RF、CMOS、Touch Controller、 MEMS)
  - **HB LED fully-automatic process**
  - **MEMS**
  - **III-V**



Si Wafer Reclaim

- 12” Wafer Reclaim
- Capacity: 120K / month
- Separated Cu & Non Cu Line

Advanced clean technology
- 20nm/ 16nm Particle
- Low trace metal (<5E9)

Complete particle inspection (SP1-DLS & SP2)

Complete polishing process
- Single side polish
- Double side polish
- Final Haze polish

Super flatness (GBIR<0.5μm)

Products

Trading (Agent/Distributor)

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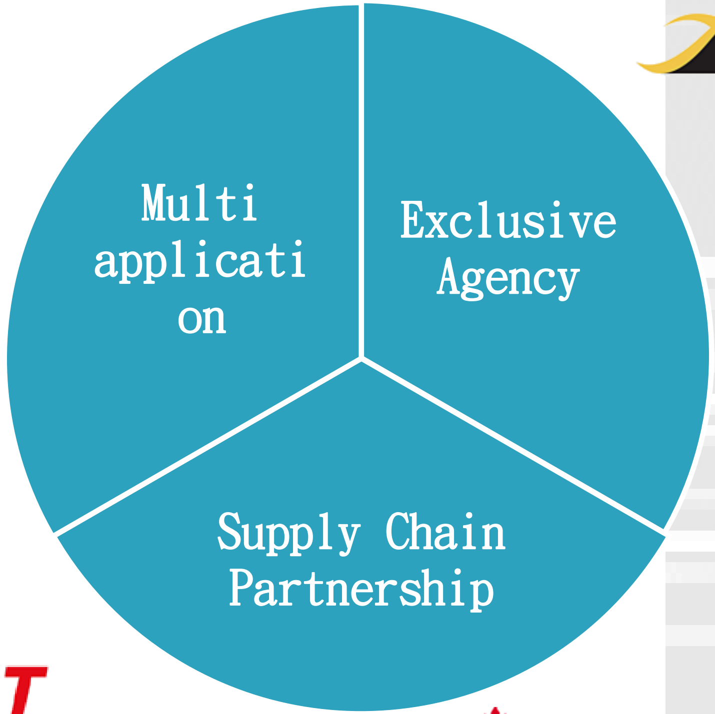


Multi application

Exclusive Agency

Supply Chain Partnership

ExOne
DIGITAL PART MATERIALIZATION

Canon

ReVera

RAVE

ECO-SNOW SYSTEMS

POONGSAN MICROTEC

FerroTec

Hirata

USHIO

UCP
PLASMA TECHNOLOGIES

VLSI Standards Incorporated

FRT

NAKAN

Kensington
LABORATORIES

Verity
INSTRUMENTS, INC.

OAI

xradia
insight in 3D

AE ADVANCED ENERGY®

Plasma-Therm

KLA Tencor
Already there

e²

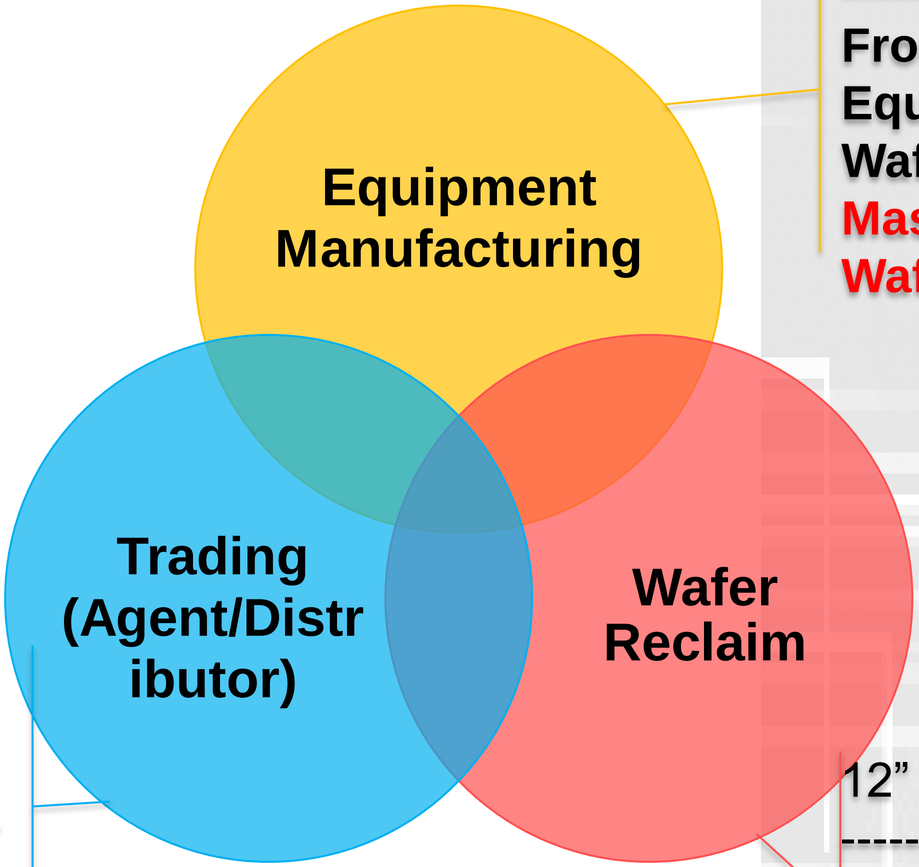
RUDOLPH
RESEARCH
ANALYTICAL

タカノ株式会社

AYUMI INDUSTRY CO.,LTD.
Ayumi
アユミ工業株式会社

NST [주]엔에스티
NST INC.

Product-based Extension



Wet Process Equipment

Front-end Wet Process Equipment

Wafer Support System

Mass Spectrometer

Wafer Reclaim

Semiconductor and Optoelectronics Process Equipment

AMOLED

Advanced Process Miniaturization

12" Wafer Reclaim

SiC Wafer Reclaim

China Manufacturing Base

Q & A

Thank You!